



FIG. 1

### ETHERM Thermal Management Feasibility Analysis

**Quick-Start Directions:**

- Enter geometry and conditions:
 

**Valid Ranges:** Outside of these ranges, accuracy may decrease.

Enclosure Volume: 142in<sup>3</sup> - 3723in<sup>3</sup>

Electronics Volume: 20% - 80% of Enclosure Volume

Power Dissipated: 10W - 250Watts

Ambient Temperature: 20-65C

Heat Sink Area: 2-5 times the area of a face on the cube
- Temperature Limit: The maximum tolerable electronics temperature. For integrated circuit chips, use "case temperature."
- Click the icon to calculate the results.

Plastic Housing  
Heat Source not in contact with housing (PCB on standoffs)  
Airflow depends greatly.

**INPUT:**

Enclosure Vol: 1000cm<sup>3</sup>

Electronics Vol: 300cm<sup>3</sup>

Power: 43W

Ambient Temp: 50C

Heat Sink Area: 1000cm<sup>2</sup>

Circuit Temp Limit: 90C

100

102

104

106

108

110

114

116

118

Fig. 2

Figure 1 consists of 12 histograms arranged in a single column. Each histogram represents the distribution of the number of non-zero elements in the vector  $x$  for a specific value of  $n$ , ranging from 10 to 120 in increments of 10. The x-axis for all histograms is labeled 'x' and ranges from 0 to 120. The y-axis is labeled 'count' and ranges from 0 to 100. The histograms show that as  $n$  increases, the distribution of  $x$  becomes increasingly concentrated around zero. For  $n=10$ , the distribution is broad and low, with a peak count of approximately 10. As  $n$  increases, the peak at zero becomes much more prominent, reaching a count of approximately 100 for  $n=120$ . The distributions for larger  $n$  values are also narrower, indicating that the number of non-zero elements in  $x$  is more predictable as the dimensionality increases.





